

LOW POWER DUAL SPST HI-SPEED USB 2.0 (480MBPS) SWITCH
IDTUS8032

Description

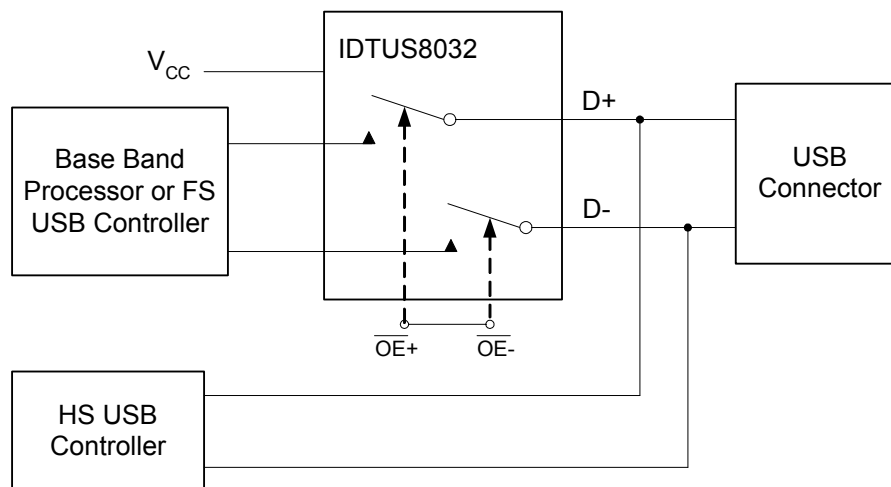
The IDTUS8032 is a low power, dual SPST 2-port hi-speed USB 2.0 switch. This part is configured as a single pole, single throw switch and is optimized for switching or isolating a hi-speed (480 Mbps) source or a hi-speed and full-speed (12 Mbps) source. The IDTUS8032 is compatible with the requirements of USB2.0 and features an extremely low ON capacitance (C_{ON}) of 6.0 pF. The wide bandwidth of this device (>500 MHz) exceeds the bandwidth needed to pass the 3rd harmonic, resulting in signals with minimum edge and phase distortion. Superior channel-to-channel crosstalk also minimizes interference.

The IDTUS8032 contains circuitry on the D+/D- pins which allows the device to withstand an overvoltage condition. This device is also designed to minimize current consumption even when the control voltage applied to the \overline{OE} pin is lower than the supply voltage (V_{CC}). This feature is especially valuable to portable applications such as cell phones, allowing for direct interface with the general purpose I/Os of the baseband processor.

Applications

- Notebooks, PDAs
- Cellular phones, Digital cameras
- LCD monitors, TVs, Set-top Boxes

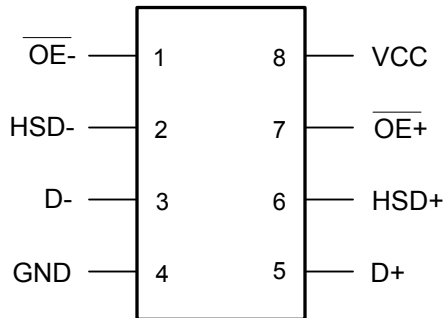
Application Block Diagram



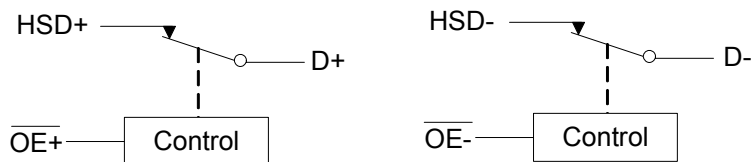
Features

- Low On capacitance, 4.5 pF (typical)
- Low On resistance, 3.5Ω (typical)
- Low power consumption (3 mA maximum)
 - 1 mA typical ICCT over and expanded control voltage range ($V_{IN}=2.6$ V, $V_{CC}=3.6$ V)
- Wide -3dB bandwidth, > 500 MHz
- 8K I/O to GND ESD protection
- Power OFF protection when $V_{CC}=0$ V, D+/D- pins can tolerate up to 3.6 V
- Packaged in RoHS compliant 8-pin SOIC or 8-pin MSOP

Pin Assignment (8-pin SOIC and 8-pin MSOP)



Analog Symbol



Truth Table

$\overline{OE+}, \overline{OE-}$	Function
H	Disconnect
L	D+, D- = HSD

Pin Descriptions

Pin Name	Pin Description
$\overline{OE+}, \overline{OE-}$	Bus switch enable.
D+, D-, HSD+, HSD-	Data ports.
NC	No connect.

Absolute Maximum Ratings

Stresses above the ratings listed below can cause permanent damage to the IDTUS8032. These ratings, which are standard values for IDT commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range. All voltages referenced to ground.

Symbol	Parameter	Rating
V_{CC}	Supply Voltage	-0.5 V to 5.5 V
V_S	DC Input Voltage ¹	-0.5 V to 5.5 V
V_{IN}	DC Switch Voltage ¹ HSD D+, D-	-0.5 V to V_{CC} to 0.3 V -0.5 V to 4.6 V
	DC Input Diode Current	-50 mA
	DC Output Current	50 mA
	Storage Temperature	-65°C to 150°C
	ESD (Human Body Mode) All Pins I/O to GND	7.5 kV 8 kV

Recommended Operating Conditions ²

Symbol	Parameter	Rating
V_{CC}	Supply Voltage	3.0 V to 3.6 V
V_{IN}	DC Switch Voltage	0V to V_{CC}
	DC Input Diode Current	0V to V_{CC}
	Storage Temperature	-40°C to +85°C

Note 1: The input and output negative voltage ratings may be exceeded if the input and output diode current ratings are observed. DC switch voltage may never exceed 3.6 V.

Note 2: Control input must be held HIGH or LOW and it must not float.

DC Electrical Characteristics

Unless stated otherwise, typical values are at 25°C

Symbol	Parameter	Conditions	V _{CC} (V)	T _A = -40°C to +85°C			Units
				Min.	Typ.	Max.	
V _{IK}	Clamp Diode Voltage	I _{IN} = -18 mA	3.0	0		-1.2	V
V _{IH}	Input Voltage HIGH		3.0 to 3.6	1.3			V
			3.6	1.7			
V _{IL}	Input Voltage LOW		3.0 to 3.6			0.5	V
			3.6			0.7	
I _{IN}	Control Input Leakage	V _{IN} = 0V to V _{CC}	3.6	-1.0		1.0	μA
I _{OZ}	OFF State Leakage	0 ≤ HSD ≤ V _{CC}	3.6	-2.0		2.0	μA
I _{OFF}	Power OFF Leakage Current (D+, D-)	V _{IN} = 0V to 3.6 V V _{CC} = 0V	0	-2.0		2.0	μA
R _{ON}	Switch On Resistance ¹	V _{IN} = 0.4 V, I _{ON} = -8 mA	3.0		3.5	10.0	Ω
ΔR _{ON}	Delta R _{ON} ²	V _{IN} = 0.4 V, I _{ON} = -8 mA	3.0		0.35		Ω
R _{ON} Flatness	R _{ON} Flatness ¹	V _{IN} = 0V to 1.0 V, I _{ON} = -8 mA	3.0		2.0		Ω
I _{CC}	Quiescent Supply Current	V _{IN} = 0V or V _{CC} , I _{OUT} = 0	3.3		300		μA
I _{CCT}	Increase in I _{CC} Current per Control voltage and V _{CC} levels	V _{IN} = 2.6 V, V _{CC} = 3.6 V	3.6		1	3	mA

Notes:

1. Measured by the voltage drop between Dn, HSD, Dn pins at the indicated current through the switch. On Resistance is determined by the lower of the voltage on the two ports.
2. Guaranteed by design.

AC Electrical Characteristics

Unless stated otherwise, typical values are for V_{CC} = 3.3 V at 25°C

Symbol	Parameter	Conditions	V _{CC} (V)	T _A = -40°C to +85°C			Units
				Min.	Typ.	Max.	
t _{ON}	Turn ON Time, \overline{OE} to output	V _{IN} = 0.8 V, R _L = 50Ω, C _L = 5 pF	3.0 to 3.6		15.0	30.0	ns
t _{OFF}	Turn OFF Time, \overline{OE} to output	V _{IN} = 0.8 V, R _L = 50Ω, C _L = 5 pF	3.0 to 3.6		12.0	30.0	ns
t _{PD}	Propagation Delay ¹	R _L = 50Ω, C _L = 5 pF	3.3		0.25		ns
O _{IRR}	OFF Isolation (non-adjacent)	R _T = 50Ω, f = 240 MHz	3.0 to 3.6		-35.0		dB
Xtalk	Non-adjacent Channel Crosstalk	R _T = 50Ω, f = 240 MHz	3.0 to 3.6		-55.0		dB
BW	-3dB Bandwidth	R _T = 50Ω, C _L = 0 pF	3.0 to 3.6		500		MHz
		R _T = 50Ω, C _L = 5 pF			450		

Note 1: Guaranteed by design.

USB Hi-Speed Related AC Electrical Characteristics

Symbol	Parameter	Conditions	V _{CC} (V)	T _A = -40°C to +85°C			Units
				Min.	Typ.	Max.	
t _{SK(O)}	Channel-to-channel Skew ¹	C _L = 5 pF	3.0 to 3.6		50.0		ps
t _{SK(P)}	Skew of the Opposite Transitions of the Same Output ¹	C _L = 5 pF	3.0 to 3.6		20.0		ps
t _J	Total Jitter ¹	R _L = 50Ω, C _L = 5 pF, t _R = t _F = 500 ps at 480 Mbps (PRBS = 2 ¹⁵ - 1)	3.0 to 3.6		200		ps

Note 1: Guaranteed by design.

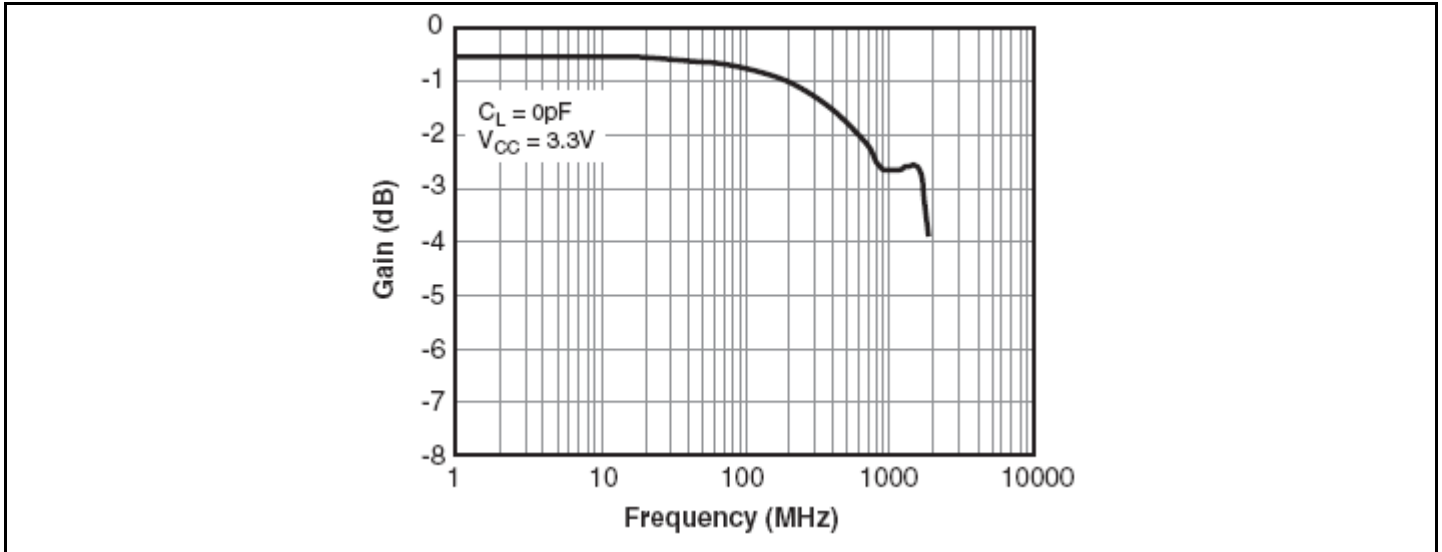
Capacitance

Symbol	Parameter	Conditions	T _A = -40°C to +85°C			Units
			Min.	Typ.	Max.	
C _{IN}	Control Pin Input Capacitance	V _{CC} = 0V		1.0		pF
C _{ON}	D1 _n , D2 _n , Dn ON Capacitance	V _{CC} = 3.3, \overline{OE} = 0V		4.5		pF
C _{OFF}	D1 _n , D2 _n , OFF Capacitance	V _{CC} and \overline{OE} = 3.3		1.7		pF

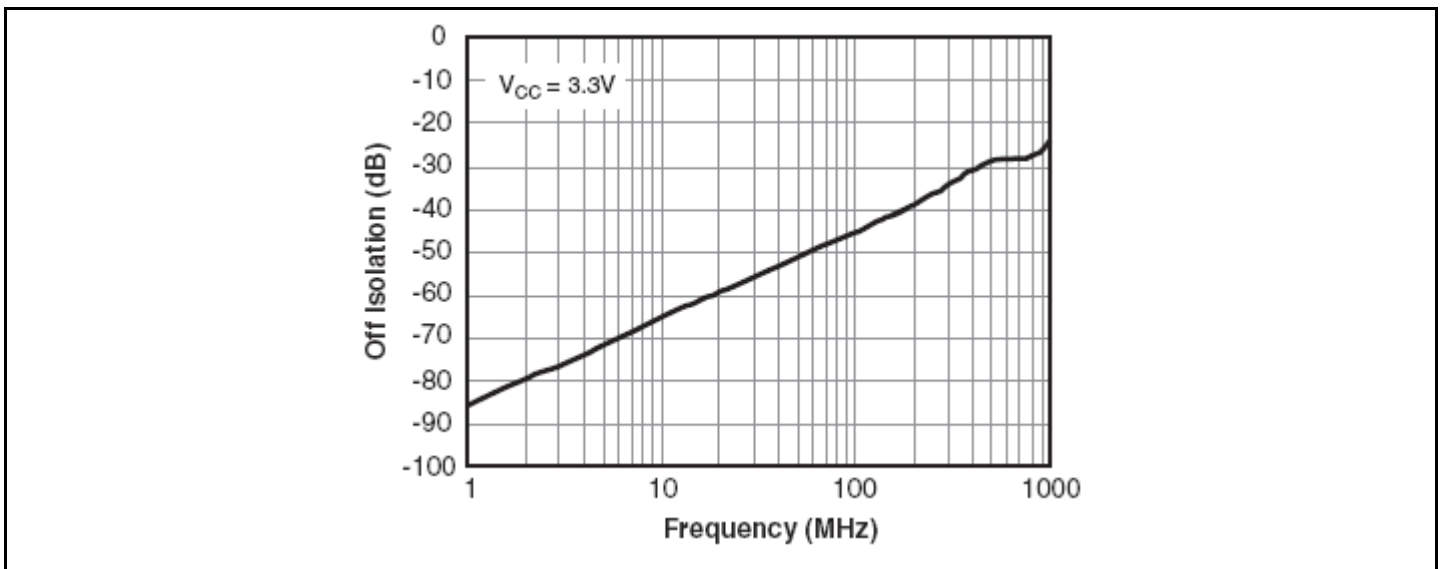
Thermal Characteristics

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Thermal Resistance Junction to Ambient	θ _{JA}	Still air		150		°C/W
	θ _{JA}	1 m/s air flow		140		°C/W
	θ _{JA}	3 m/s air flow		120		°C/W
Thermal Resistance Junction to Case	θ _{JC}			40		°C/W
Thermal Resistance Junction to Top of Case	Ψ _{JT}	Still air		20		°C/W

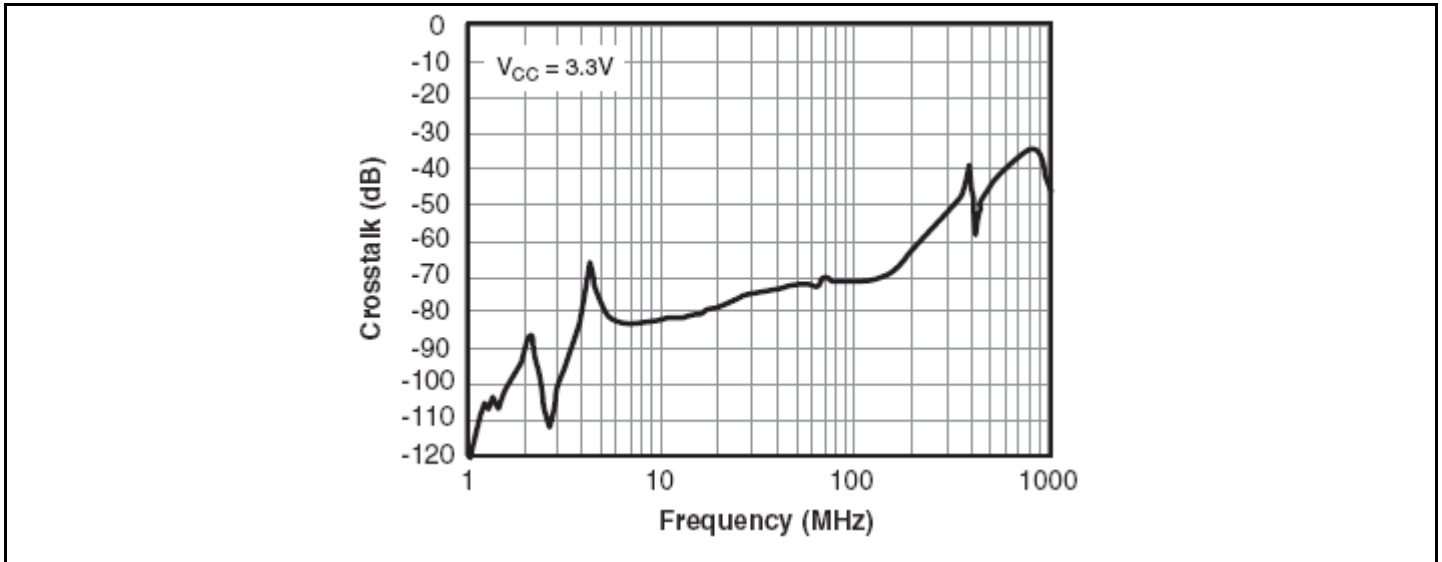
Test Circuits and Timing Diagrams



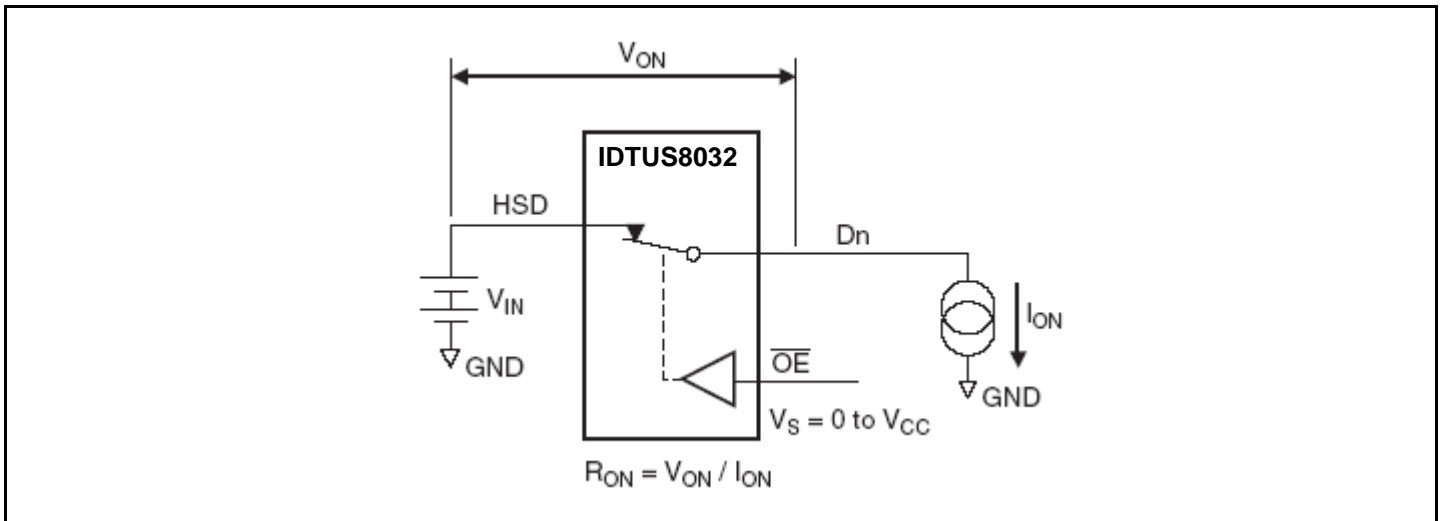
Gain vs. Frequency



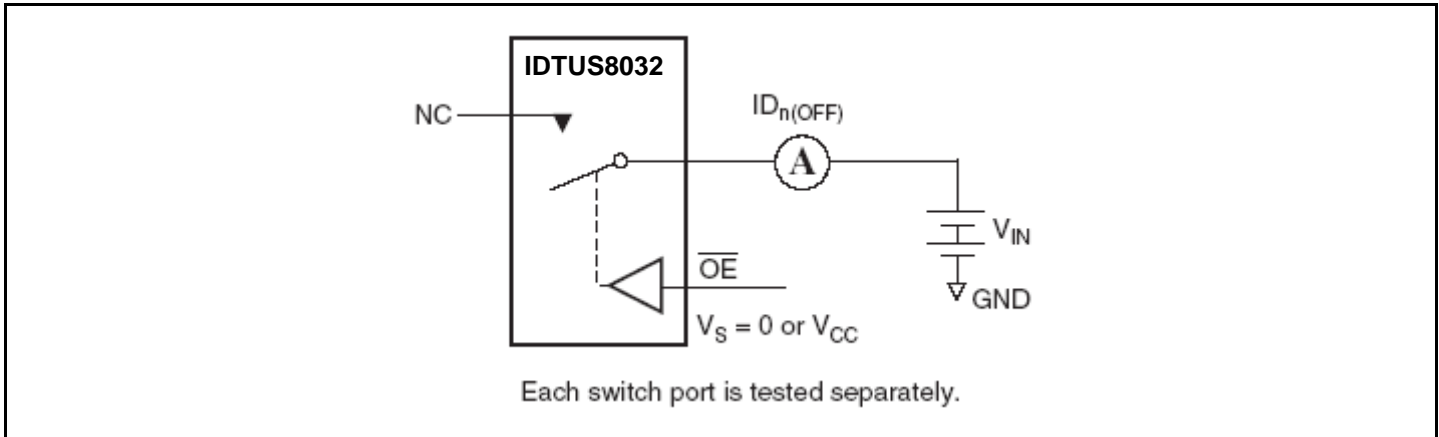
OFF Isolation



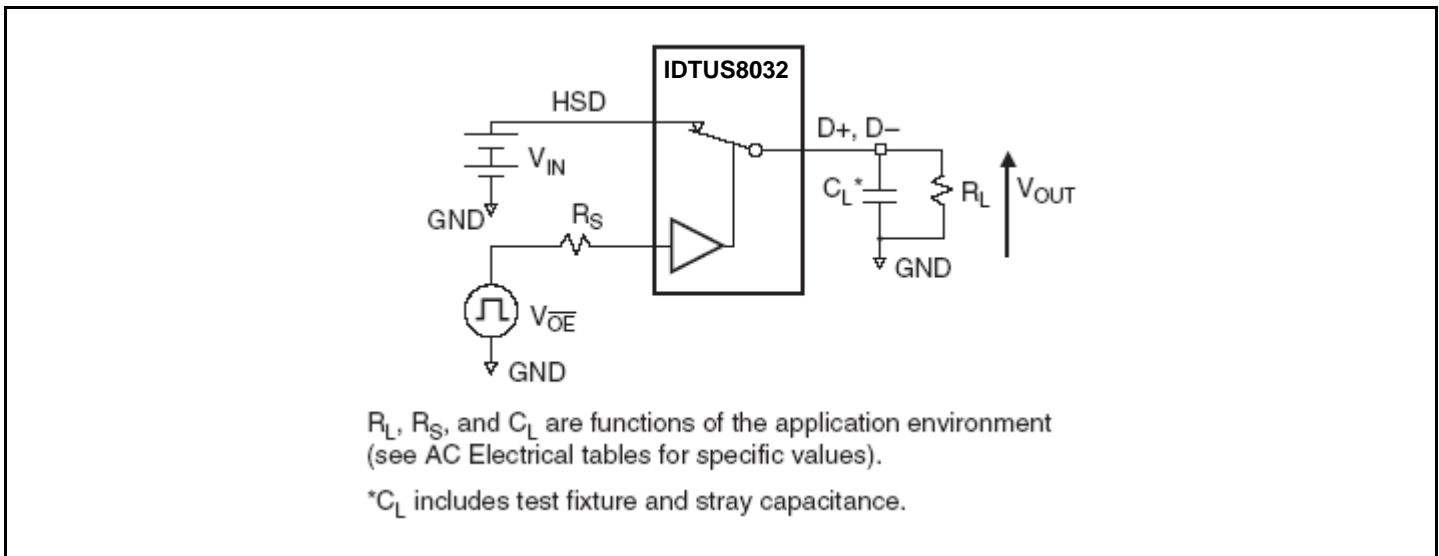
Crosstalk



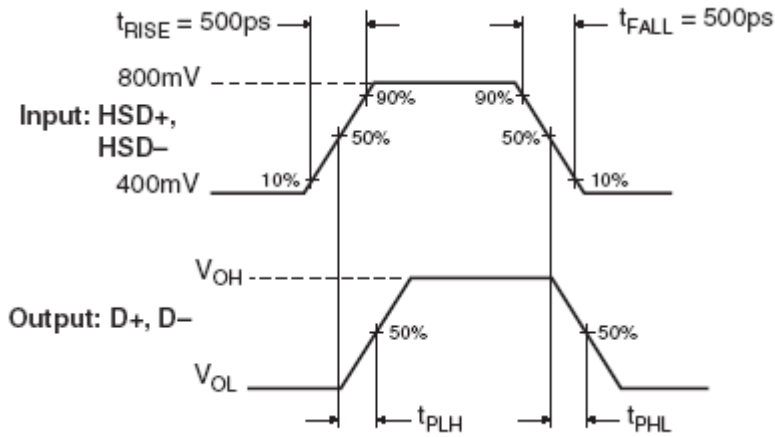
On Resistance



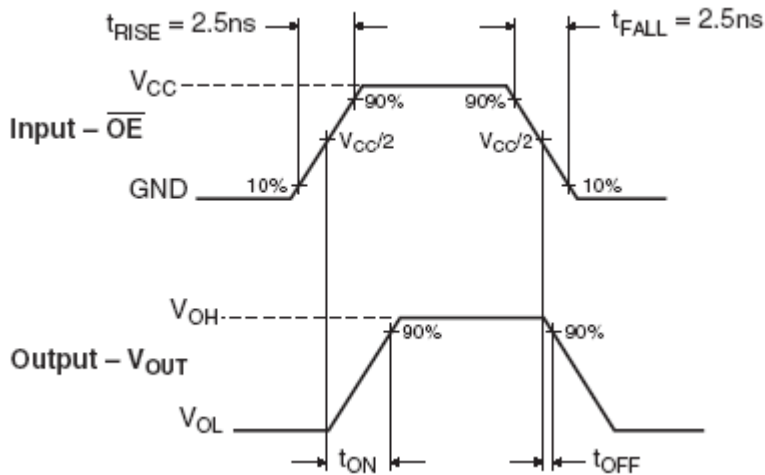
OFF Leakage



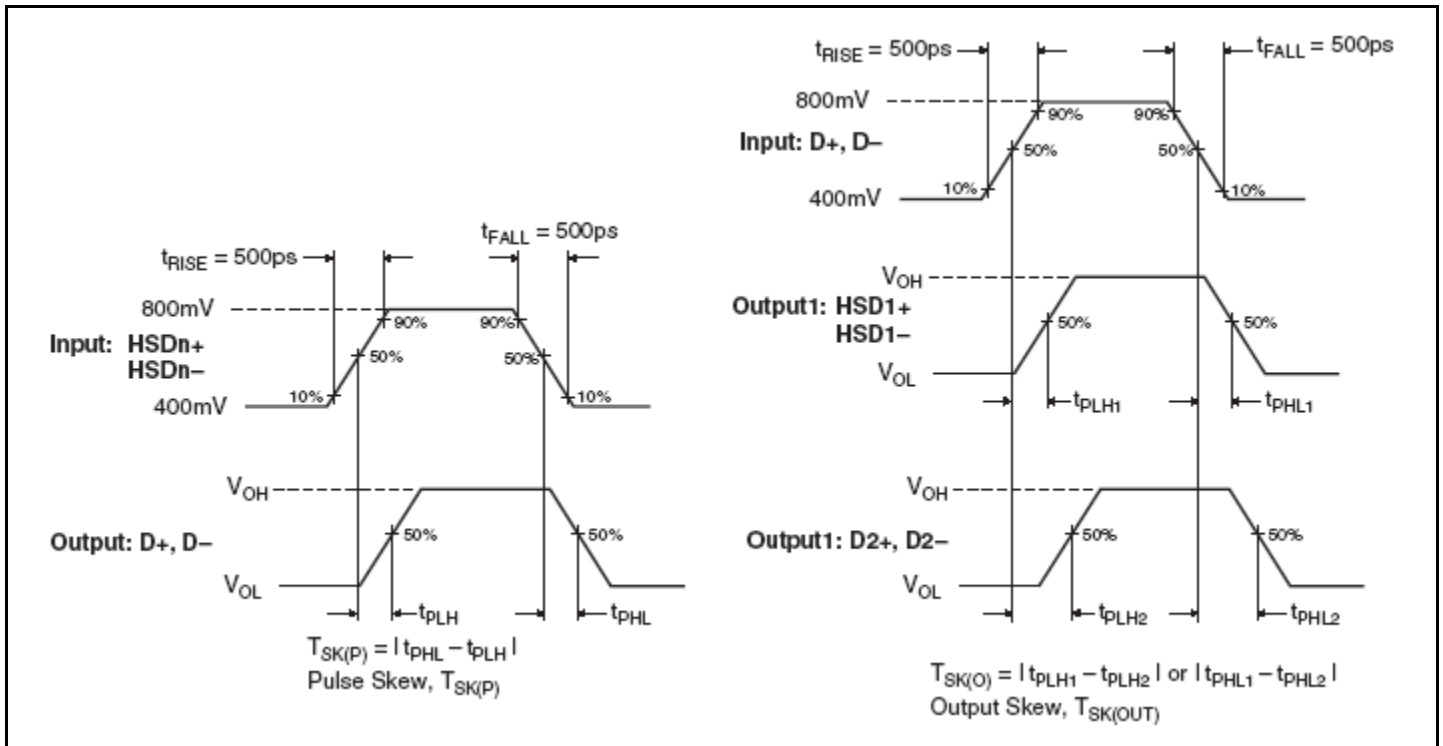
AC Test Circuit Load



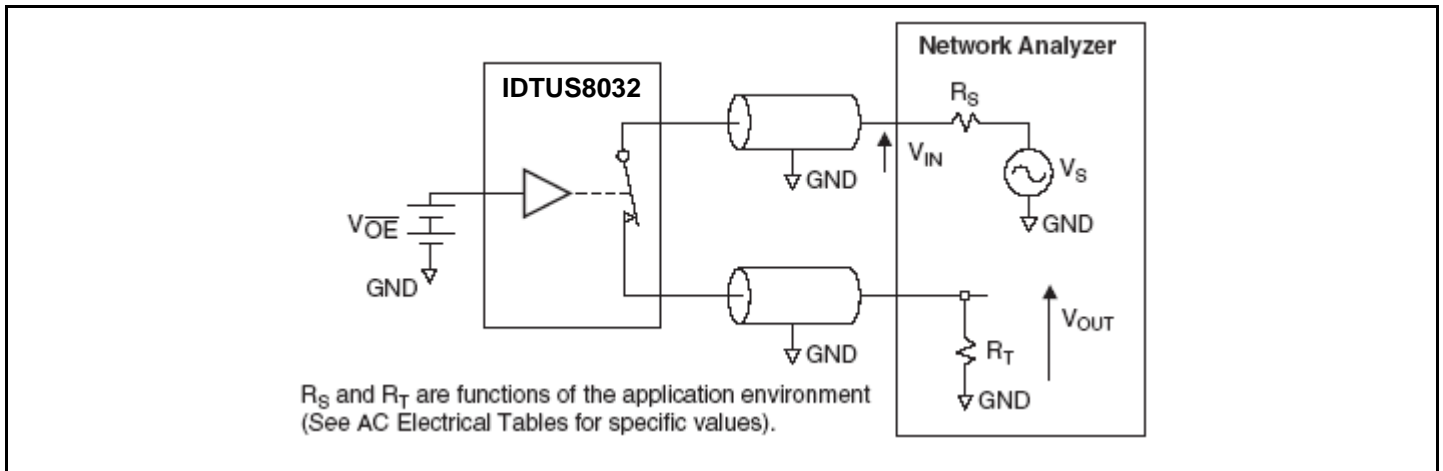
Switch Propagation Delay Waveforms (T_{PD})



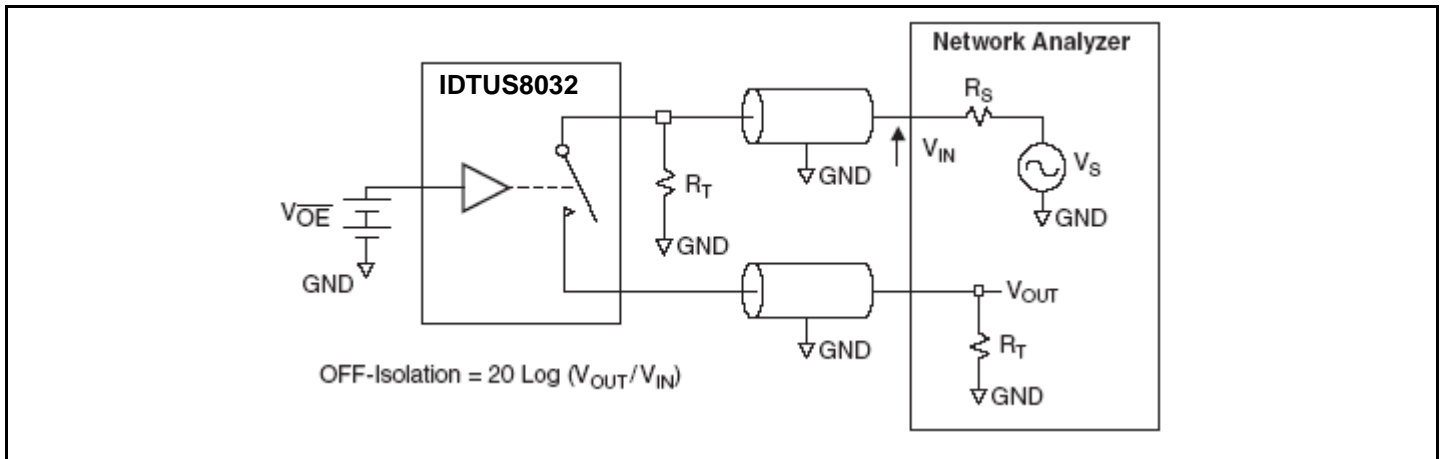
Turn ON / Turn OFF Waveform (T_{ON} / T_{OFF})



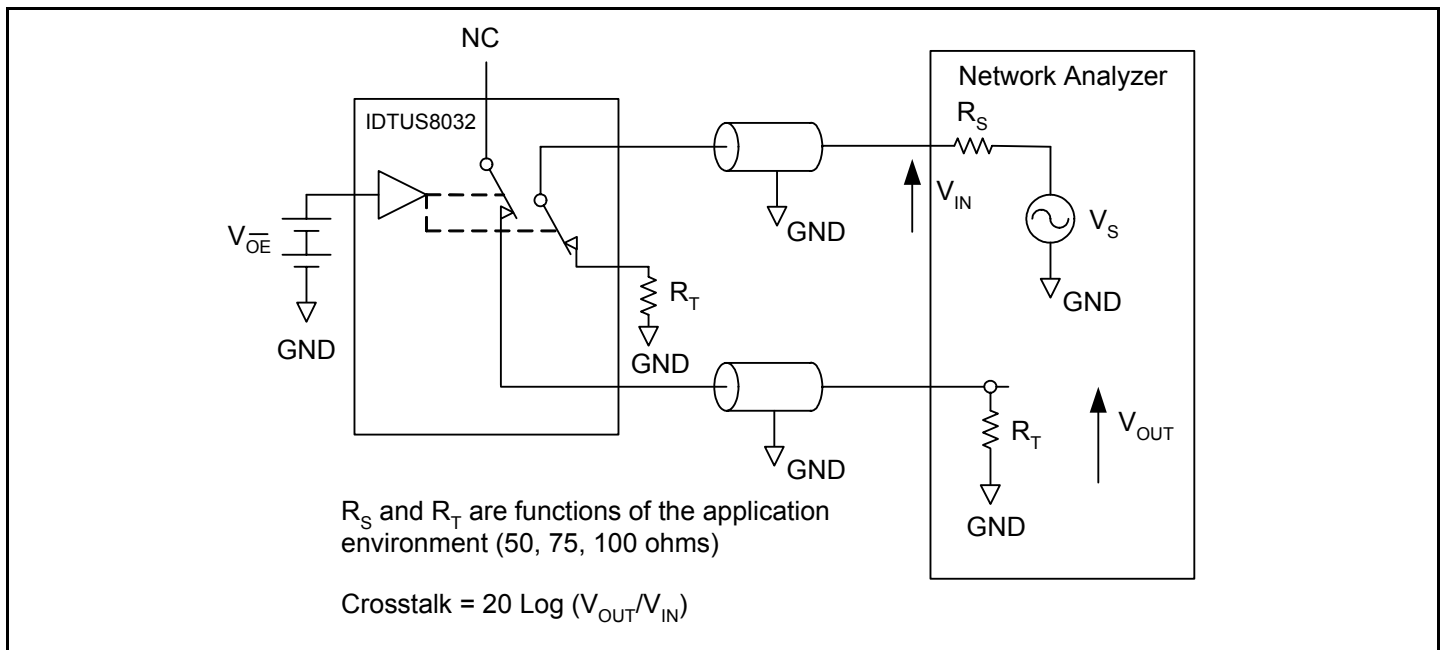
Switch Skew Tests



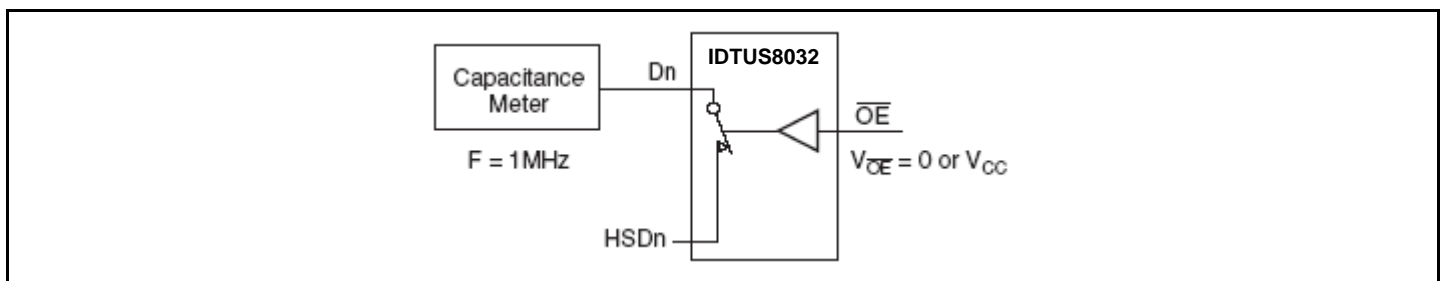
Bandwidth



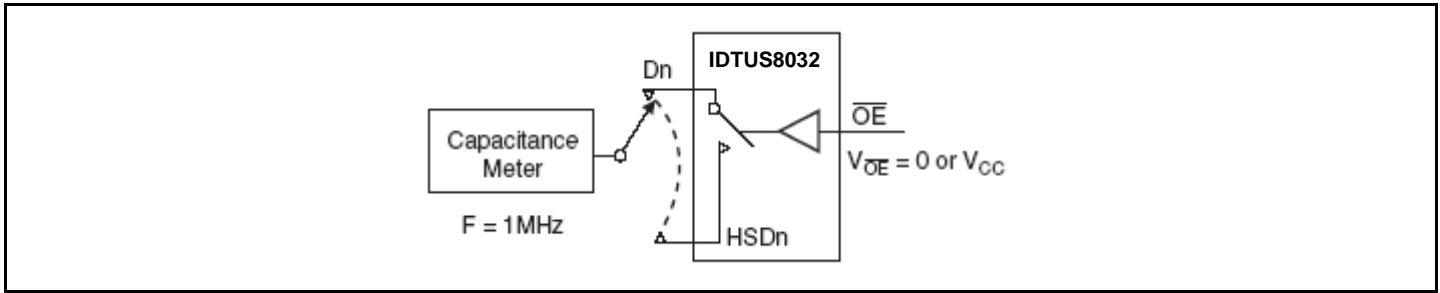
Channel OFF Isolation



Non-Adjacent Channel-to-Channel Crosstalk

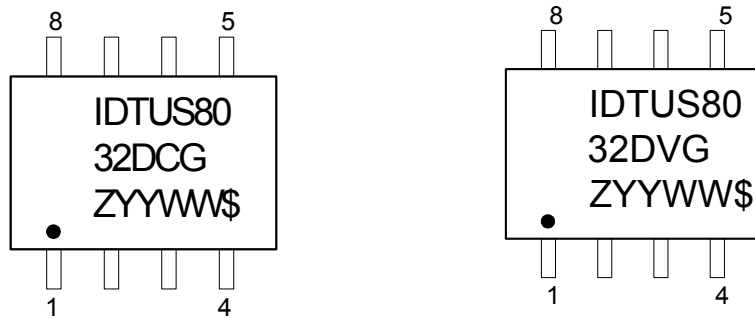


Channel ON Capacitance



Channel OFF Capacitance

Marking Diagrams



Notes:

1. "Z" is the device step (1 to 2 characters).
2. YYWW is the last two digits of the year and week that the part was assembled.
3. "\$" is the assembly mark code.
4. "G" after the two-letter package code designates RoHS compliant package.
5. "I" at the end of part number indicates industrial temperature range (if applicable).
6. Bottom marking: country of origin if not USA.

Thermal Characteristics for 8MSOP

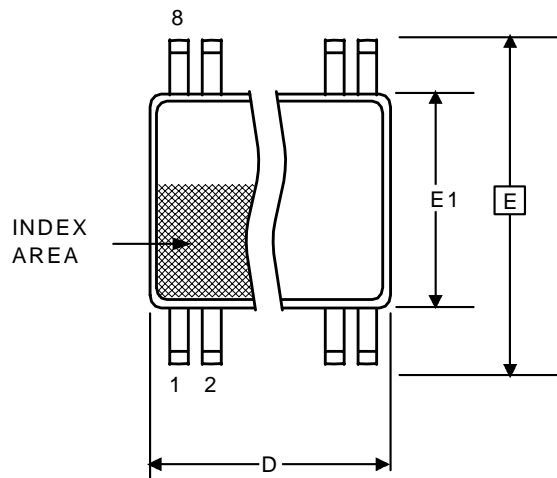
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Thermal Resistance Junction to Ambient	θ_{JA}	Still air		95		°C/W
Thermal Resistance Junction to Case	θ_{JC}			48		°C/W

Thermal Characteristics for 8SOIC

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Thermal Resistance Junction to Ambient	θ_{JA}	Still air		150		°C/W
	θ_{JA}	1 m/s air flow		140		°C/W
	θ_{JA}	3 m/s air flow		120		°C/W
Thermal Resistance Junction to Case	θ_{JC}			40		°C/W
Thermal Resistance Junction to Top of Case	Ψ_{JT}	Still air		20		°C/W

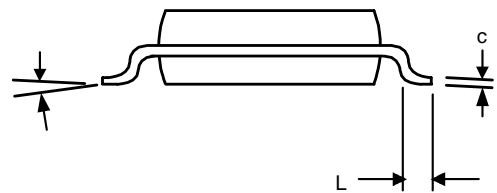
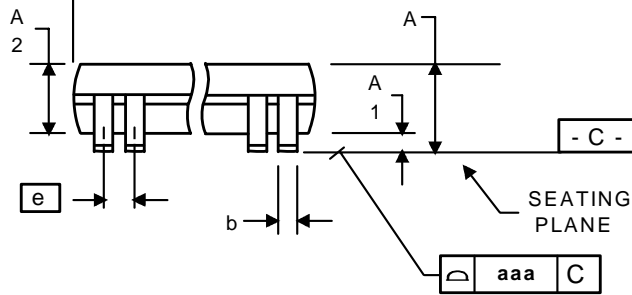
Package Outline and Package Dimensions (8-pin MSOP, 3.00 mm Body)

Package dimensions are kept current with JEDEC Publication No. 95



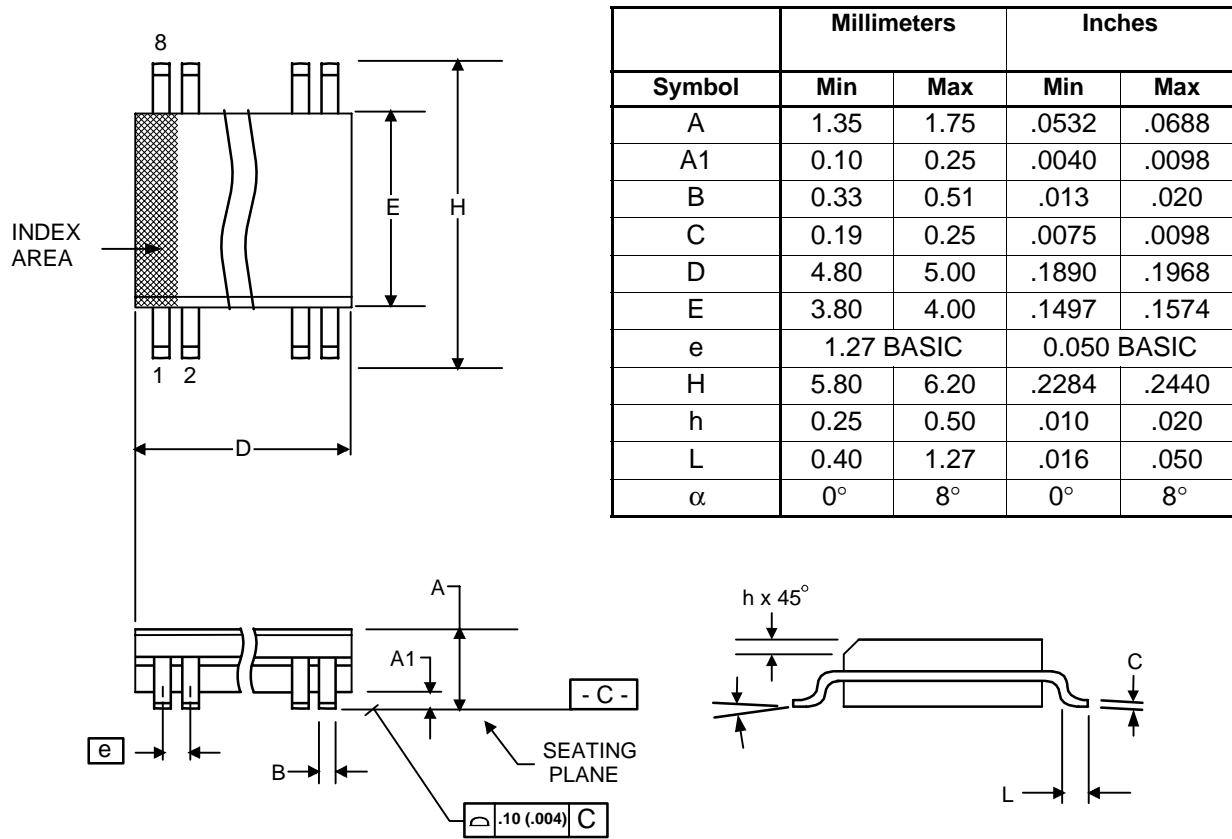
Symbol	Millimeters		Inches*	
	Min	Max	Min	Max
A	--	1.10	--	0.043
A1	0	0.15	0	0.006
A2	0.79	0.97	0.031	0.038
b	0.22	0.38	0.008	0.015
C	0.08	0.23	0.003	0.009
D	3.00 BASIC		0.118 BASIC	
E	4.90 BASIC		0.193 BASIC	
E1	3.00 BASIC		0.118 BASIC	
e	0.65 Basic		0.0256 Basic	
L	0.40	0.80	0.016	0.032
α	0°	8°	0°	8°
aaa	-	0.10	-	0.004

*For reference only. Controlling dimensions in mm.



Package Outline and Package Dimensions (8-pin SOIC, 150 Mil. Body)

Package dimensions are kept current with JEDEC Publication No. 95



Ordering Information

Part / Order Number	Marking	Shipping Packaging	Package	Temperature
US8032DCG	see page 12	Tubes	8-pin SOIC	0 to +70° C
US8032DCG8		Tape and Reel	8-pin SOIC	0 to +70° C
US8032DVG		Tubes	8-pin MSOP	0 to +70° C
US8032DVG8		Tape and Reel	8-pin MSOP	0 to +70° C

Parts that are ordered with a "G" after the two-letter package code are the Pb-Free configuration and are RoHS compliant.

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